

FIG-1

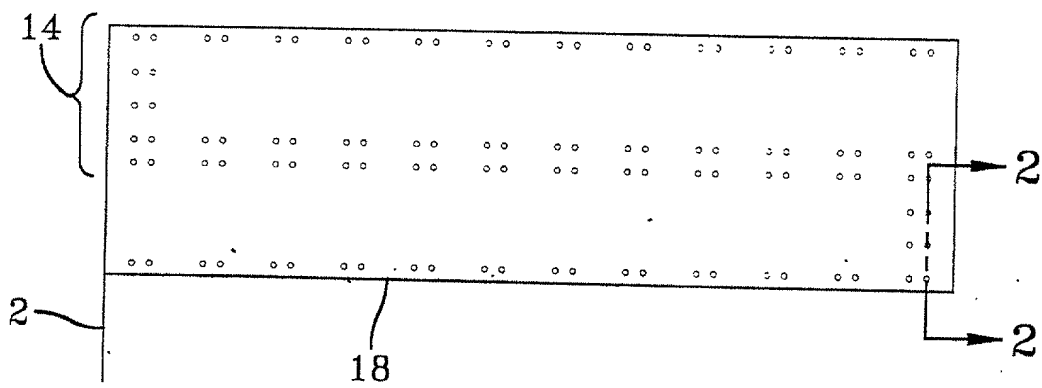


FIG-2

This exploded perspective view shows the assembly of the device. At the top, a layer of small circular components, labeled 20, is shown being positioned onto a substrate 14. The substrate 14 has a grid of circular features. Below the substrate 14 is a layer of small circular components, labeled 150, which are being positioned onto a substrate 157. The substrate 157 has a grid of circular features. The layer 150 is positioned between the substrate 14 and the substrate 157. The layer 150 is also labeled 152 and 153. The substrate 157 is also labeled 156. The layer 150 is positioned between the substrate 14 and the substrate 157. The layer 150 is also labeled 152 and 153. The substrate 157 is also labeled 156. The layer 150 is positioned between the substrate 14 and the substrate 157. The layer 150 is also labeled 152 and 153. The substrate 157 is also labeled 156.

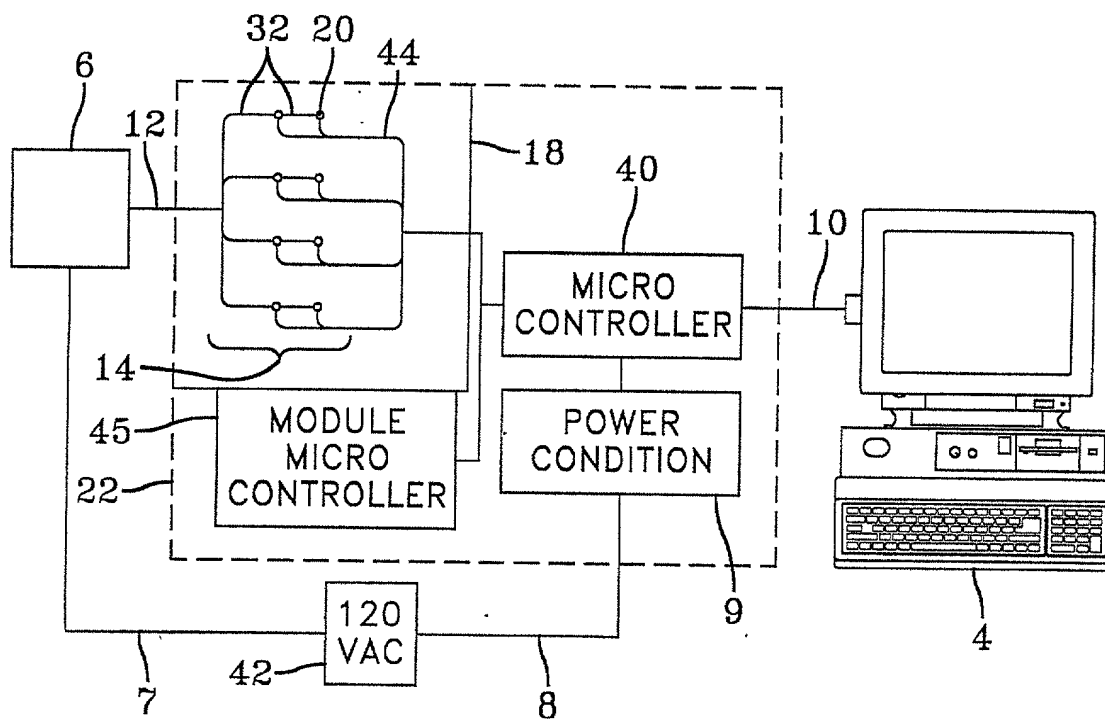


FIG-4

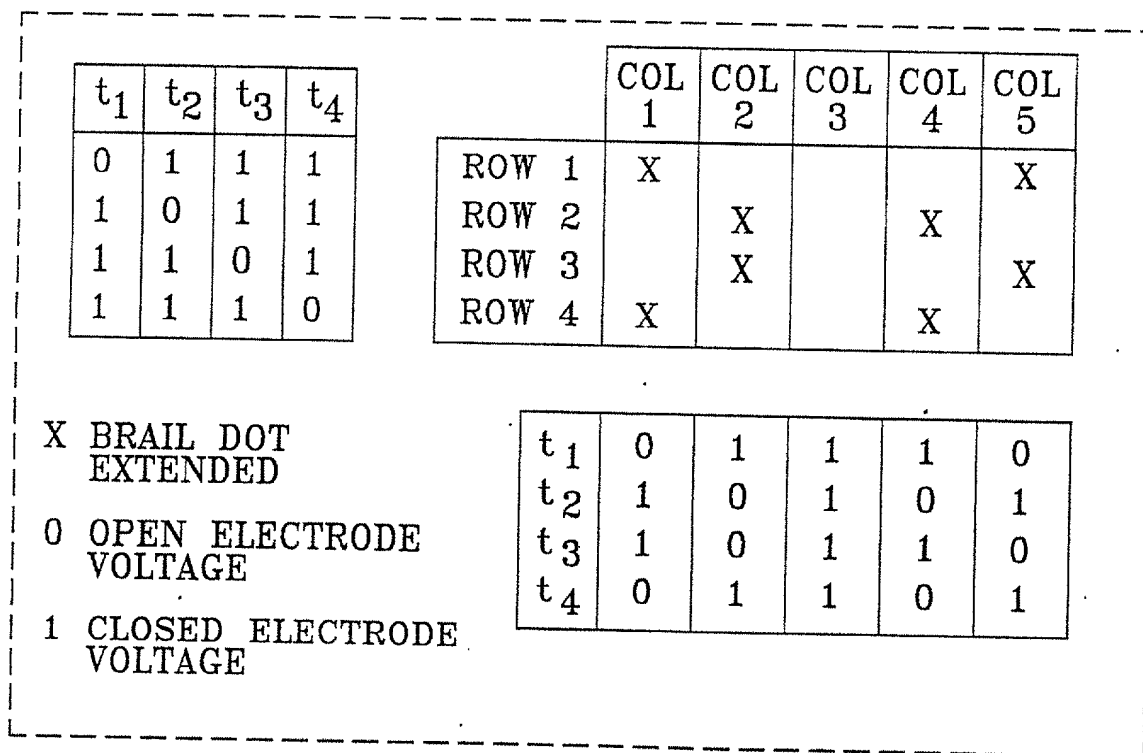


FIG - 5

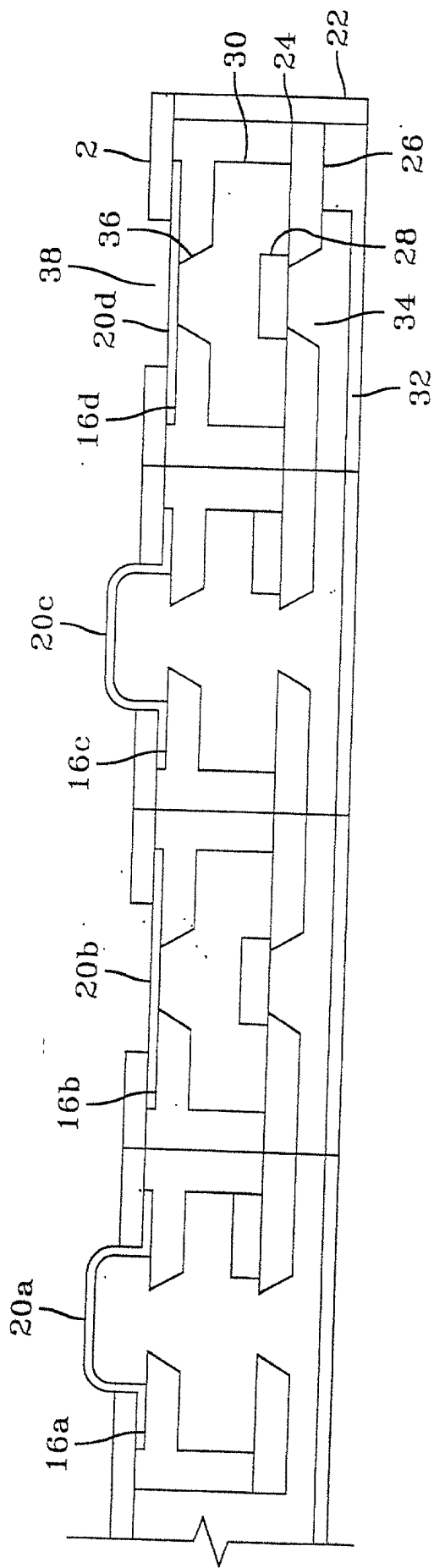
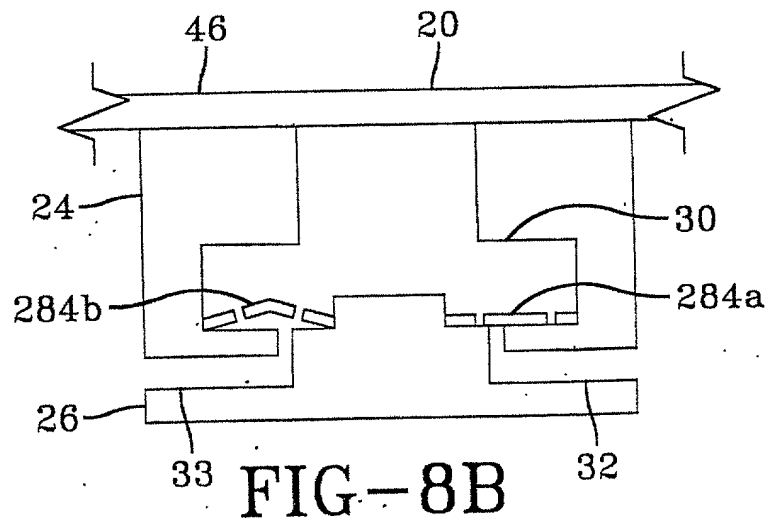
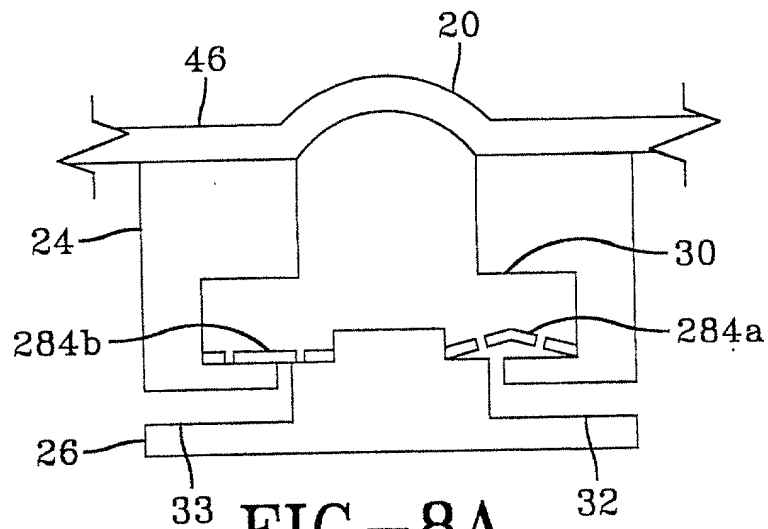
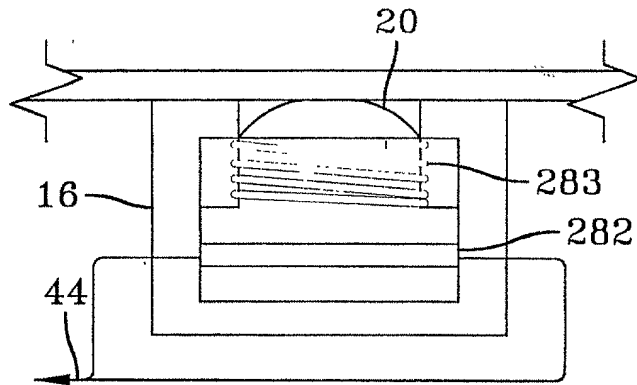


FIG-6



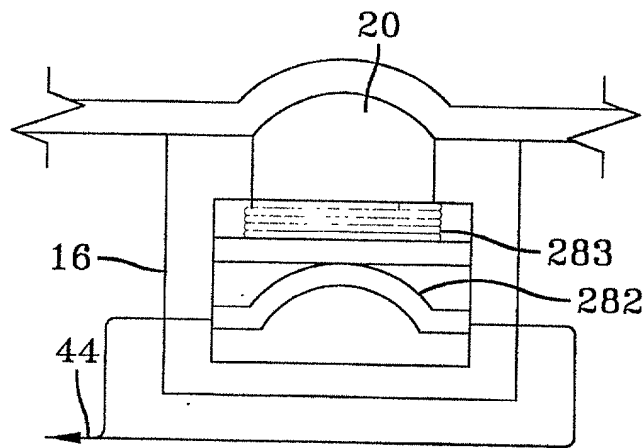






TO MICROCONTROLLER

FIG-9A



TO MICROCONTROLLER

FIG-9B

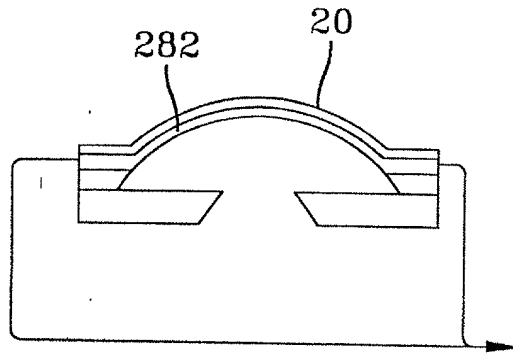


FIG-10A

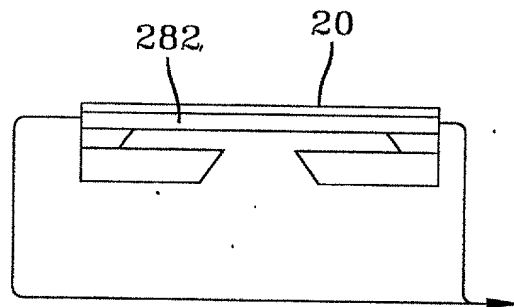


FIG-10B

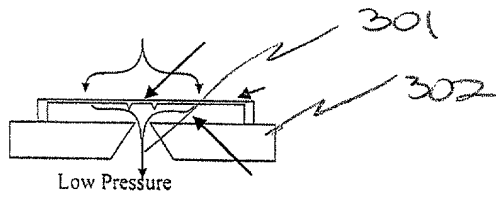


FIG - 11A

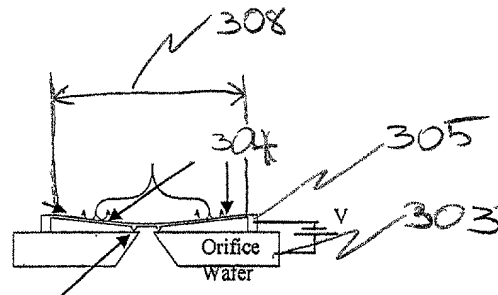


FIG - 11B

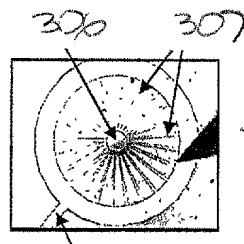


FIG - 11C

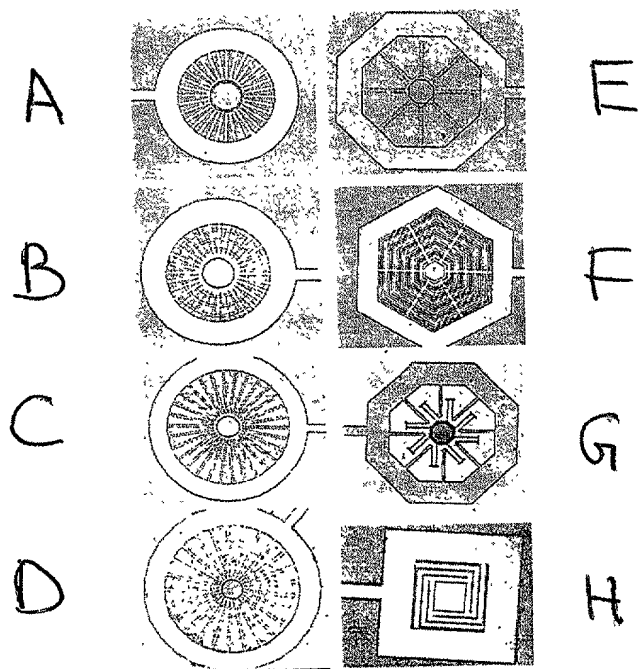


FIG - 12